

# SSC8030GN4

#### **N-Channel Enhancement Mode MOSFET**

#### Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub>	l <sub>D</sub>
30V	1.00)/	7mΩ@10V	40.4
	±20V	9mΩ@4.5V	48A

#### > Description

This device uses advanced trench technology to provide excellent RDSON and low gate charge. This device is suitable for use as a load switch or in PWM applications.

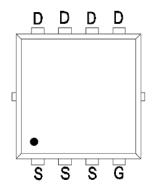
# Applications

- Load Switch
- NB/PC
- DCDC conversion

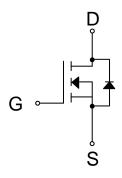
### > Ordering Information

Device	Package	Shipping
SSC8030GN4	PDFN3.3X3.3-8L	5000/Reel

# > Pin Configuration



PDFN3.3X3.3-8L (Top View)



**Pin Configuration** 



Marking

(YW: Internal Traceability Code)



## ➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V <sub>DSS</sub>	Drain-to-Source Voltage		30	V
V <sub>GSS</sub>	Gate-to-Source Volta	ge	±20	V
	Ocation of David Comments	T <sub>C</sub> =25℃	48	^
l <sub>D</sub>	Continuous Drain Current d	T <sub>C</sub> =100°C	27	A
	Continuous Dunin Comment 3	T <sub>A</sub> =25℃	15.6	^
IDSM	Continuous Drain Current <sup>a</sup> Pulsed Drain Current <sup>b</sup>	T <sub>A</sub> =70°C	11.5	A
I <sub>DM</sub>	Pulsed Drain Curren	Pulsed Drain Current <sup>b</sup>		Α
<u> </u>	Daniel Biraination 2	Tc=25℃	26	10/
P <sub>D</sub>	Power Dissipation <sup>c</sup>	Itage $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ ent b $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ H Single Pulse H Single Pulse perature	10.6	W
D	Daniel Biraination 2	T <sub>A</sub> =25℃	2.7	34/
P <sub>DSM</sub>	Power Dissipation <sup>a</sup>	T <sub>A</sub> =70°C	1.7	W
I <sub>AS</sub>	Avalanche Current <sup>b</sup> L=0.5mH \$	17	Α	
Eas	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		72	mJ
TJ	Operation junction temperature		-55~150	%
T <sub>STG</sub>	Storage temperature range		-55~150	℃

## ➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	46	°C/W
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance	4.7	C/VV

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation  $P_D$  is based on  $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.



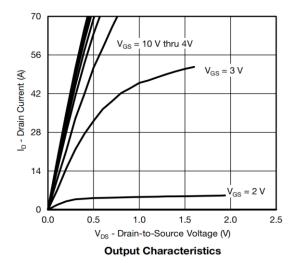


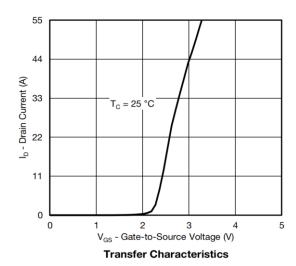
# $\succ$ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

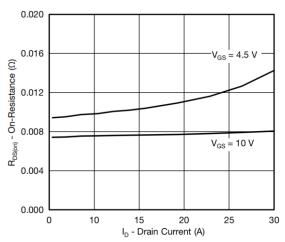
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250uA$	1	1.5	3	V
Drain-Source On-Resistance	D	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A		7	9.5	m0
Dialii-Source Oil-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A		9	12.5	mΩ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	lgss	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 15A		20		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A		0.8	1.3	٧
Input Capacitance	Cıss	\ -45\/\\ -0\/		986		
Output Capacitance	Coss	$V_{DS} = 15V$ , $V_{GS} = 0V$ , $f = 1MHz$		133		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>	T - TIVINZ		111		
Total Gate Charge	Q <sub>G</sub>	\\ -40\\\\ -45\\		18		
Gate to Source Charge	Q <sub>GS</sub>	$V_{GS} = 10V, V_{DS} = 15V,$ $I_{D} = 13A$		2		nC
Gate to Drain Charge	Q <sub>GD</sub>	1D – 13A		3		
Turn-on Delay Time	T <sub>D(ON)</sub>			7		
Rise Time	Tr	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V,		5		
Turn-off Delay Time	T <sub>D(OFF)</sub>	$R_L = 0.75\Omega$ , $R_G = 3\Omega$		24		ns
Fall Time	T <sub>f</sub>			6		
Diode Recovery Time	Trr	I <sub>F</sub> =20A, di/dt=100A/us		10		ns
Diode Recovery Charge	Qrr	I <sub>F</sub> =20A, di/dt=100A/us		14		nC

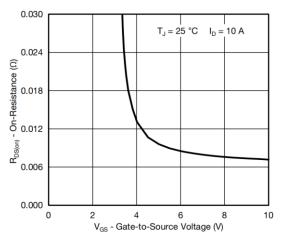


# > Typical Performance Characteristics (T<sub>A</sub>=25℃ unless otherwise noted)



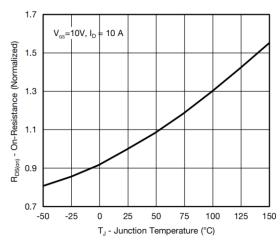


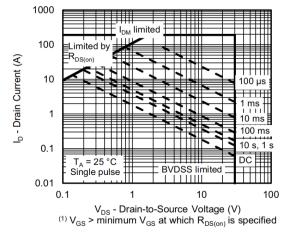




On-Resistance vs. Drain Current and Gate Voltage

On-Resistance vs. Gate-to-Source Voltage



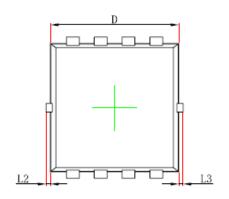


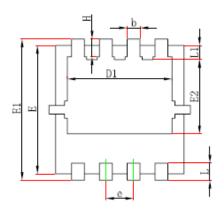
On-Resistance vs. Junction Temperature

Safe Operating Area, Junction-to-Ambient



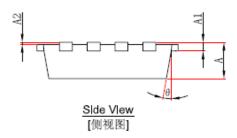
# Package Information





Top Vlew [顶视图]

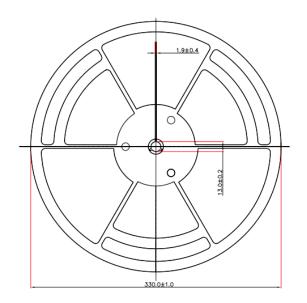
Bottom View [背视图]

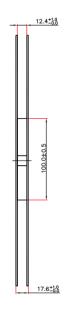


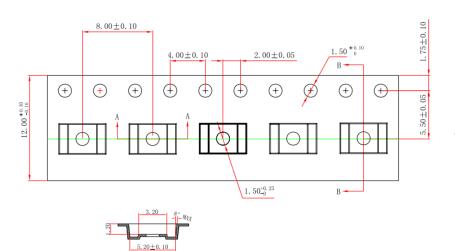
Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min.	Max.	Min.	Max.		
Α	0.650	0.850	0.026	0.033		
A1	0.152	REF.	0.006	REF.		
A2	0~0.	05	0~0.0	0~0.002		
D	2.900	3.100	0.114	0.122		
D1	2.300	2.600	0.091	0.102		
E	2.900	3.100	0.114	0.122		
E1	3.150	3.450	0.124	0.136		
E2	1.535	1.935	0.060	0.076		
b	0.200	0.400	0.008	0.016		
е	0.550	0.750	0.022	0.030		
L	0.300	0.500	0.012	0.020		
L1	0.180	0.480	0.007	0.019		
L2	0~0.100		0~0.0	004		
L3	0~0.100		0~0.0	004		
Н	0.315	0.515	0.012	0.020		
θ	9°	13°	9°	13°		



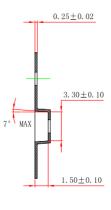
# > Tape and Reel







A-A



В-В



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